PCN Number:		20180111004					PCN Da		Janu	ary 18, 2018
Title: Datasheet for TPS564208										
Customer Contact: PCN Manage			Manager	ger			Dept:		Quality Services	
Proposed 1 <sup>st</sup> Ship Date: April			18, 2018							
Change Type:										
Assembly Site			Design					Wafer Bump Site		
Assembly Process			□ Data Sheet					Wafer Bump Material		
Assembly Materials			Part number change				Щ	Wafer Bump Process		
Mechanical Specification			Test Site			Щ		r Fab Site		
Packing/Shipping/Labeling			Test Process			Щ		r Fab Materials		
									Wafe	r Fab Process
Notification Details										
Description of Change:										
Texas Instruments Incorporated is announcing an information only notification.										
The product datasheet(s) is being updated as summarized below.										
II Toyac										
TEXAS INSTRUMENTS TPS564208										
Changes from Revision A (October 2017) to Revision B Page										
- Changes from Revision A (October 2011) to Revision b										
Changed the I <sub>VIN</sub> MAX value From: 780 μA To: 820 μA in the <i>Electrical Characteristics</i>										
The datasheet number will be changing.										
Device Family			Change From:						Change To:	
TPS564208				SLVSDG0A					SLVSDG0B	
http://www.ti.com/product/TPS564208										
Reason for Change:										
To accurately reflect device characteristics.										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
Electrical specification performance changes as indicated above.										
Changes to product identification resulting from this PCN:										
None.										
Produ	ct Affected:									
TPS56	54208DDCR	TP	S5642	08D	DCT					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com